

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 05156459
PUBLICATION DATE : 22-06-93

APPLICATION DATE : 06-12-91
APPLICATION NUMBER : 03323021

APPLICANT : HITACHI BOODEN KK;

INVENTOR : IGAWA KIYOKAZU;

INT.CL. : C23C 18/40 H05K 3/18

TITLE : ELECTROLESS COPPER PLATING SOLUTION

ABSTRACT : PURPOSE: To prevent blister of a through hole base material and to improve plating appearance, depositing rate and liquid stability by adding an iodine compound and α,α' -dipyridyl into an electroless copper plating solution.

CONSTITUTION: The electroless copper plating solution consists of an aqueous solution, containing of a cupric salt, a complexing agent, a reducing agent and a pH controlling agent such as alkali hydroxide, as a basic composition. Furthermore, the iodine compound and α,α' -dipyridyl are added into the basic composition. Conc. of the iodine compound in the plating solution is preferably 5-100mg/l and conc. of α,α' -dipyridyl is preferably 5-100mg/l. The deposited copper low in plating deposit stress is obtained by the electroless copper plating solution composition.

COPYRIGHT: (C)1993,JPO&Japio